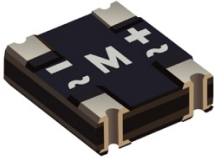


MATERIAL DECLARATION SHEET



Material Number	CD-MMBL110S			
Product Line	Semiconductor Products			
Compliance Date	2021/7/29			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Metal	18.86	Continuous filament glass fibers	65997-17-3	25.10%	13.922530%	55.47
				Phosphorus-based epoxy resin	Confidential	23.11%	12.819253%	
				Inorganic filler	Confidential	12.07%	6.695300%	
				Copper	7440-50-8	39.45%	21.883147%	
				Zinc	7440-66-6	0.20%	0.110941%	
				Nickel	7440-02-0	0.05%	0.027735%	
				Chromium	7440-47-3	0.01%	0.005547%	
2	Epoxy	Plastic	10.17	Silicon Dioxide	7631-86-9	57.14%	17.099818%	29.92
				Epoxy	9003-36-5	42.86%	12.820182%	
3	Solder Cream	Metal	0.94	Lead	7439-92-1	88%	2.428235%	2.76
				Tin	7440-31-5	10%	0.276471%	
				Silver	7440-22-4	2%	0.055294%	
4	Dice	Others	3.35	Silicon	7440-21-3	87.50%	8.618363%	9.85
				Boron	7440-42-8	0.0001%	0.000010%	
				Phosphorous	7723-14-0	0.0001%	0.000010%	
				Silicon dioxide	60676-86-0	12.250%	1.206985%	
				Lead oxide	1317-36-8			
Aluminum oxide	1344-28-1							

MATERIAL DECLARATION SHEET



				Nickel	7440-02-0	0.250%	0.024632%	
5	Terminal Plating	Metal	0.68	Tin	7440-31-5	100%	2.000000%	2
		Total weight	34					

This Document was updated on: Same as compliance date.

Important remarks:

- 1. Please see Certificate of Compliance for exemptions used.**